

1 (Supplementary Information)

2 **Disordered Spin Gapless Semiconducting CoFeCrGa Heusler Alloy Thin**
3 **Films on Si (100): Experiment and Theory**

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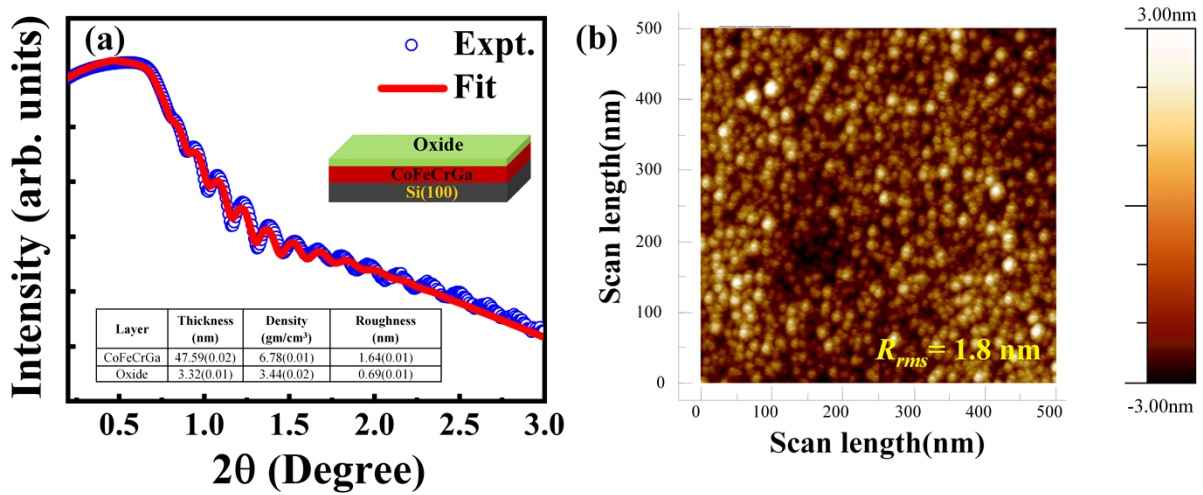
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13 **S1. Surface and Morphological Analysis: XRR and AFM**

14 The Fig. S1 (a) shows the XRR profile recorded for B-550 film sample of nominal thickness
15 50nm. The presence Kiessig fringes even up to $2\theta \sim 4$ assures the good surface quality and
16 less intermixing at the interface ¹. The recorded curve was fitted using X-ray reflectivity
17 (segmented V.1.2) software through simulation using the model which assumes the formation
18 of a native oxide layer over the top surface of the CFCG film as shown in the inset of the Fig.
19 S1 (a). The thickness, density, and roughness of CFCG and oxide layers evaluated through the
20 fitted data is shown the inset of the bottom left of the Fig. S1 (a). The simulated curve gives
21 the thickness of CFCG film ~ 47.59 nm and that of oxide layer as ~ 3.32 nm. The density of the
22 CFCG film (~ 6.78 g/cc) is found to be nearly close to its bulk density value of 7.47 g/cc, which
23 suggests that the grown film is non-porous and densely packed.

24 The topography of the CFCG film was investigated using AFM technique. The sample was
25 scanned over an area of 500×500 nm² in tapping mode. The cantilever of the dimension
26 $225 \times 30 \times 3$ μm^3 , embedded with a platinum coated tip of radius < 10 nm was used in tapping
27 mode. The Fig. S1 (b) shows one of the AFM images recorded on the 50 nm thin CFCG film.
28 It can be seen that film is quite homogeneous and clearly exhibits a granular microstructure.
29 The grains formed are of spherical shape with an average size of ~ 25 nm. The root mean square
30 roughness (R_{rms}) of the film is ~ 1.80 nm which is equivalent to that obtained from XRR
31 measurement (~ 1.64 nm)



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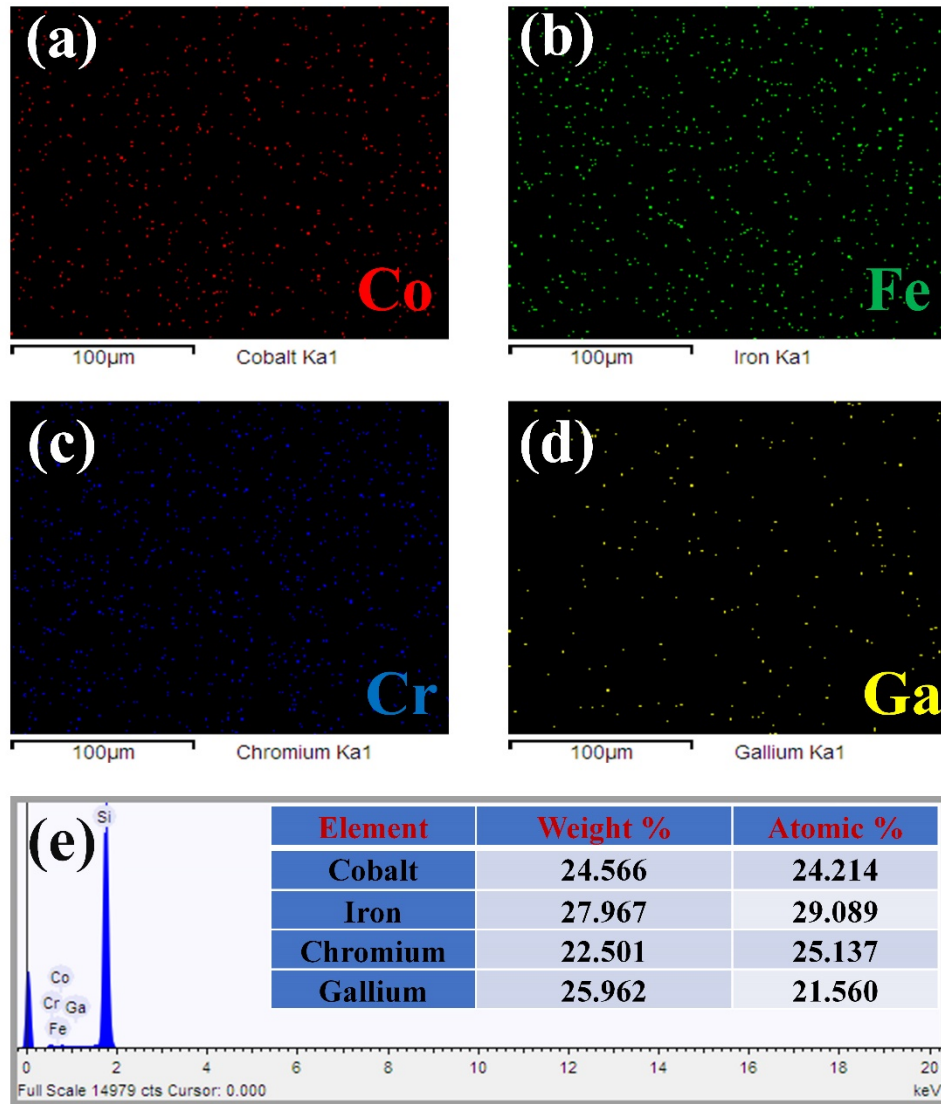
2 **Fig. S1 (a)** XRR spectra of the B-550 CFCG thin film. The simulation model and the values of the thickness,
 3 density, and roughness (along with the errors in the parenthesis) extracted through the fitted data are shown in the
 4 top right and bottom left of the main panel, respectively. **(b)** The topographical AFM image of B-550 sample with
 5 its root mean square roughness (R_{rms}).

6 **S3. Compositional Analysis: EDAX**

7 The EDAX measurement was performed over B-550 film to quantify and analyse the different
 8 elements present in the sample as shown in Fig. S2 (a-e). Figures S2 (a, b, c & d) show the
 9 elemental mapping of individual Co, Fe, Cr and Ga elements on $\sim 250 \mu m^2$ area of the sample
 10 which depicts that all the elements are uniformly distributed over the film surface and the film
 11 sample is slightly Gallium deficient. The EDS spectrum (counts/sec vs keV) for Co, Fe, Cr,
 12 Ga, and Si atoms is shown in Fig. S2 (e). The table in the inset shows the normalized
 13 composition of Co, Fe, Cr and Ga elements in terms of weight and atomic percentage which
 14 confirmed their stoichiometry to be $Co_{24.2}Fe_{29.1}Cr_{25.1}Ga_{21.6}$. The excess Fe and deficient Ga
 15 may be possibly causing the disorder in the film sample.

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2 **FIG S2.** Elemental mapping of (a) Cobalt, (b) Iron, (c) Chromium and (d) Gallium on $\sim 250\mu\text{m}^2$ area of the
 3 sample. (e) EDS spectrum (counts/sec vs keV) for Co, Fe, Cr, Ga, and Si atoms with table in the inset showing
 4 the normalized weight % and atomic% of CFCG film after removing the contribution of Si (100) substrate.

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6 REFERENCES

- 7 1 N. K. Gupta, V. Barwal, S. Hait, L. Pandey, V. Mishra, L. Saravanan, A. Kumar, N.
 8 Sharma, N. Kumar, S. Husain and S. Chaudhary, *Thin Solid Films*, 2022, **756**, 139355.

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